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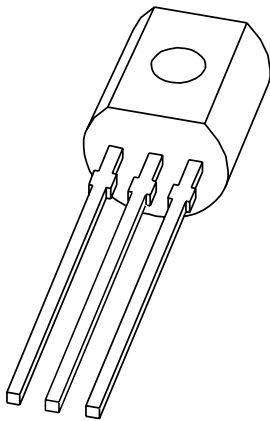
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# DATA SHEET



**BF370**

**NPN medium frequency transistor**

Product data sheet  
Supersedes data of 1999 Apr 21

2004 Nov 08

NPN medium frequency transistor

BF370

FEATURES

- Low current (max. 100 mA)
- Low voltage (max. 15 V).

APPLICATIONS

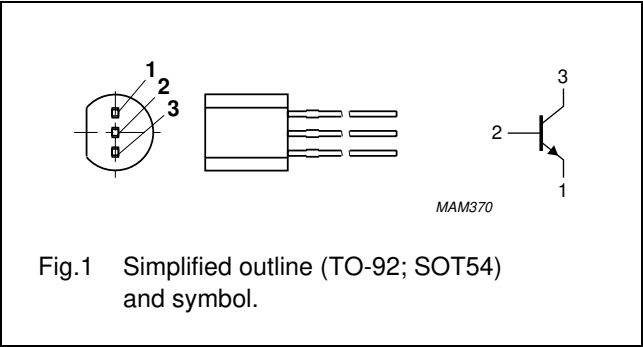
- IF preamplifiers of television receivers.

DESCRIPTION

NPN medium frequency transistor in a TO-92; SOT54 plastic package.

PINNING

PIN	DESCRIPTION
1	emitter
2	base
3	collector



ORDERING INFORMATION

TYPE NUMBER	PACKAGE		
	NAME	DESCRIPTION	VERSION
BF370	SC-43A	plastic single-ended leaded (through hole) package; 3 leads	SOT54

## NPN medium frequency transistor

BF370

## LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
$V_{CBO}$	collector-base voltage	open emitter	–	40	V
$V_{CEO}$	collector-emitter voltage	open base	–	15	V
$V_{EBO}$	emitter-base voltage	open collector	–	4.5	V
$I_C$	collector current (DC)		–	100	mA
$I_{CM}$	peak collector current		–	200	mA
$P_{tot}$	total power dissipation	$T_{amb} \leq 25\text{ °C}$ ; note 1	–	500	mW
$T_{stg}$	storage temperature		–65	+150	°C
$T_j$	junction temperature		–	150	°C
$T_{amb}$	ambient temperature		–65	+150	°C

## Note

1. Transistor mounted on an FR4 printed-circuit board.

## THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
$R_{th(j-a)}$	thermal resistance from junction to ambient	note 1	250	K/W

## Note

1. Transistor mounted on an FR4 printed-circuit board.

## CHARACTERISTICS

 $T_{amb} = 25\text{ °C}$  unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
$I_{CBO}$	collector-base cut-off current	$V_{CB} = 20\text{ V}$ ; $I_E = 0\text{ A}$	–	–	400	nA
		$V_{CB} = 20\text{ V}$ ; $I_E = 0\text{ A}$ ; $T_j = 125\text{ °C}$	–	–	30	$\mu\text{A}$
$I_{EBO}$	emitter-base cut-off current	$V_{EB} = 2\text{ V}$ ; $I_C = 0\text{ A}$	–	–	100	nA
$h_{FE}$	DC current gain	$V_{CE} = 1\text{ V}$ ; $I_C = 10\text{ mA}$	40	–	–	
$C_c$	collector capacitance	$V_{CB} = 10\text{ V}$ ; $I_E = i_e = 0\text{ A}$ ; $f = 1\text{ MHz}$	–	2.2	–	pF
$C_e$	emitter capacitance	$V_{EB} = 1\text{ V}$ ; $I_C = i_c = 0\text{ A}$ ; $f = 1\text{ MHz}$	–	–	4.5	pF
$C_{re}$	feedback capacitance	$V_{CB} = 10\text{ V}$ ; $I_C = 0\text{ A}$ ; $f = 1\text{ MHz}$	–	1.6	–	pF
$f_T$	transition frequency	$V_{CE} = 10\text{ V}$ ; $f = 100\text{ MHz}$ $I_C = 10\text{ mA}$	500	–	–	MHz
		$I_C = 40\text{ mA}$	490	–	–	MHz

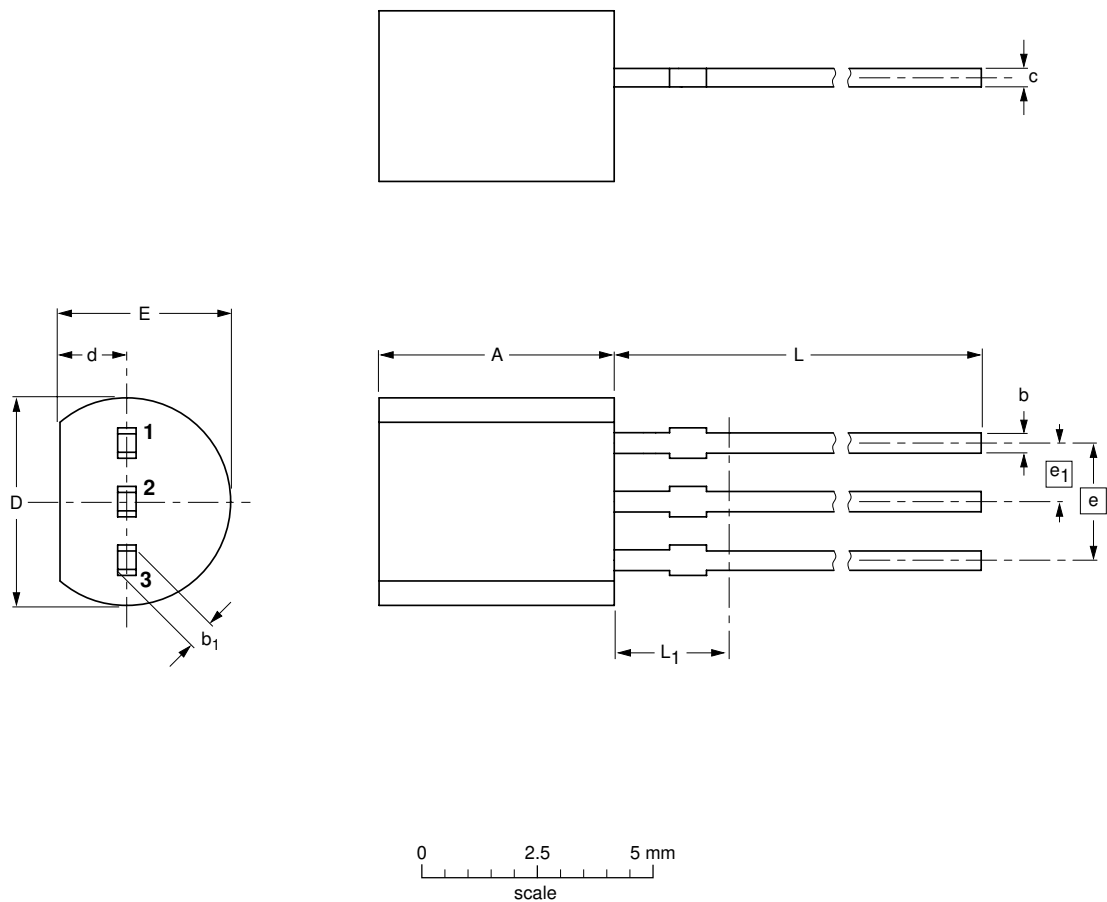
NPN medium frequency transistor

BF370

PACKAGE OUTLINE

Plastic single-ended leaded (through hole) package; 3 leads

SOT54

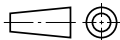


DIMENSIONS (mm are the original dimensions)

UNIT	A	b	b <sub>1</sub>	c	D	d	E	e	e <sub>1</sub>	L	L <sub>1</sub> <sup>(1)</sup> max.
mm	5.2 5.0	0.48 0.40	0.66 0.55	0.45 0.38	4.8 4.4	1.7 1.4	4.2 3.6	2.54	1.27	14.5 12.7	2.5

Note

1. Terminal dimensions within this zone are uncontrolled to allow for flow of plastic and terminal irregularities.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT54		TO-92	SC-43A			04-06-28 04-11-16

## NPN medium frequency transistor

BF370

## DATA SHEET STATUS

DOCUMENT STATUS <sup>(1)</sup>	PRODUCT STATUS <sup>(2)</sup>	DEFINITION
Objective data sheet	Development	This document contains data from the objective specification for product development.
Preliminary data sheet	Qualification	This document contains data from the preliminary specification.
Product data sheet	Production	This document contains the product specification.

## Notes

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# ***NXP Semiconductors***

## **Customer notification**

This data sheet was changed to reflect the new company name NXP Semiconductors, including new legal definitions and disclaimers. No changes were made to the technical content, except for package outline drawings which were updated to the latest version.

## **Contact information**

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